

FLIP CHIP PACKAGE STRUCTURE FOR AN IMAGE SENSOR AND AN IMAGE SENSE MODULE WITH THE FLIP CHIP PACKAGE STRUCTURE

BACKGROUND OF THE INVENTION

5 1. Field of the Invention

The present invention relates to a flip chip package structure and an image sense module, and more particularly to a flip chip package structure for an image sensor and an image sense module with the flip chip package structure.

10 2. Description of Related Art

The current package technology of an image sensor usually use the ceramic leaded chip carrier (CLCC) or plastic leaded chip carrier (PLCC) that needs the processes of embedding a die pad and wire bonding. However, the number of I/O pins of an electric element
15 become great, the thickness of the electric element becomes thin and the volume of the electric element becomes small under the requests of a slight weight, multi-function and a quick process speed.

Consequently, the conventional solder technology is limited due to the diameter of the holes in the PCB for receiving the leads of electric parts.

20 The surface mounting technology (SMT) is provided to overcome the problem of the conventional solder technology. However, the PCB cannot be used to load the current thin lead such that the leads of electric parts are arranged in an array type for enhancing the yield of

manufacturing. However, a hollow solder and a curve PCB is occurred after soldering according to great number I/O leads and a small package volume. To solve the above problem is to lessen the volume of the jelly on the chip as small as possible.

5 As described above, the chip package technology trends toward Flip chip package. The process of flip chip package needs to grow multiple bumps on the wafer and each bump is electrically connected to the circuit on a PCB such that the top of each of the bumps face the PCB and the prerequisite condition of a open sensing area of the image
10 sensor is limited. Consequently, the flip chip has a good electric property, heat dissipation and a small packaged size, but it is difficult to use the technology of flip chip on an image sensor very well.

 A conventional flip chip package structure of an image sensor in accordance with the prior art shown in Fig. 9 comprises a glass plate
15 (91) including an inner face forming a circuit (910) on the inner face of the glass plate (91) by etching. A chip (92) is soldered on the circuit near a middle portion of the glass plate (91) by using first tin balls (93) and the technology of flip chip. The circuit (910) of the glass plate (91) has two opposite sides each having a second tin ball (94) for surface
20 mounting of the circuit (910). The diameter of each of the second tin ball (94) must be greater than the thickness of the chip (92) for a good reliability. For a suitable interval between the two second tin balls (94) the area of the glass plate (91) must be enlarged. Consequently, the

enlarged glass plate (91) enlarges the volume of the image sensor. The type of the conventional flip chip package structure needs to be advantageously altered.

The present invention has arisen to mitigate and/or obviate the disadvantages of the conventional flip chip package structure.

SUMMARY OF THE INVENTION

The main objective of the present invention is to provide an improved flip chip package structure for an image sensor and an image sense module with the flip chip package structure.

To achieve the objective, the image sense module in accordance with the present invention comprises a semi-conductor image sense chip having a top face attached to a bottom face of a glass plate and multiple electric contacts formed on the semi-conductor image sense chip. A conductive interconnection circuit is formed on the bottom face of the glass plate. The conductive interconnection circuit has multiple first solder points each electrically connected to a corresponding one of the electric contacts of the semi-conductor image sense chip and multiple second solder points formed on one side of the glass plate. The multiple second solder points are adapted to be electrically connected to a printed circuit. A lens set is secured on the glass plate. The lens set includes a holder perpendicularly attached to a top face of the glass plate and having a skirt downward extending from the holder. A channel is defined in one side of the skirt for allowing the conductive

interconnection circuit extending through the holder.

Further benefits and advantages of the present invention will become apparent after a careful reading of the detailed description with appropriate reference to the accompanying drawings.

5 BRIEF DESCRIPTION OF THE DRAWINGS

Fig. 1 is a side cross-sectional view of a first embodiment of a flip chip package structure for an image sensor in accordance with the present invention;

Fig. 2 is a side cross-sectional view of a second embodiment of
10 a flip chip package structure for an image sensor in accordance with the present invention;

Fig. 3 is a bottom plan view of a glass plate of the flip chip package structure of the present invention for showing a conductive interconnection circuit thereon;

15 Fig. 4 is another embodiment of the conductive interconnection circuit on the glass plate of the present invention;

Fig. 5 is a bottom plan view of a big glass plate on which multiple conductive interconnection circuits are formed;

Fig. 6 is a bottom plan view of the big glass plate on which a
20 chip is soldered on each of the multiple conductive interconnection circuits in Fig. 5;

Fig. 7 is a side cross-sectional view of an image sense module with the flip chip package structure in Fig. 1;

Fig. 8 is a side cross-sectional view of an image sense module with the flip chip package structure in Fig. 2;

Fig. 9 is an exploded perspective view of the image sense module in Fig. 7; and

5 Fig. 10 is a side cross-sectional view of a conventional chip package structure in accordance with the prior art.

DETAILED DESCRIPTION OF THE INVENTION

Referring to the drawings and initially to Fig. 1, a flip chip package structure (1) for an image sensor in accordance with the
10 present invention comprises a semi-conductor image sense chip (10) having a top face (11) attached to a bottom face of a glass plate (20). A periphery between the semi-conductor image sense chip (10) and the glass plate (20) is underfilled with jelly-like material (12) for forming an airtight condition between the semi-conductor image sense chip (10)
15 and the glass plate (20). Multiple bonding pads (111) are formed on the top face (11) of the semi-conductor image sense chip (10). A metal soldering ball (13) is planted with a corresponding one of the multiple bonding pads (111) on the semi-conductor image sense chip (10). In the preferred embodiment of the present invention, the metal soldering
20 ball (13) is a tin ball.

A conductive interconnection circuit (21) is formed on the bottom face of the glass plate (20) and multiple first solder points (22) each electrically connected to a corresponding one of the multiple

bonding pads (111).

With reference to Fig. 3, the conductive interconnection circuit (21) forms multiple second solder points (211) on one side of the bottom face of the glass plate (20).

5 The periphery and the bottom face of the glass plate (20) are covered with an opaque mask (24). The opaque mask (24) has a through hole (not numbered) defined for allowing the semi-conductor image sense chip (10) extending through the opaque mask (24). The opaque mask (24) can prevent the light from entering the glass plate
10 (20) and influencing the quality of the collected image from the semi-conductor image sense chip (10), and form an airtight condition around the semi-conductor image sense chip (10).

With reference to Fig. 2 that shows a second embodiment of the flip chip package structure (3) for an image sensor of the present
15 invention, a second embodiment of the flip chip package structure for an image sensor comprises a semi-conductor image sense chip (30) having a top face (31) attached to a bottom face of a glass plate (20). A periphery between the semi-conductor image sense chip (30) and the glass plate (20) is underfilled with jelly-like material (12) for forming
20 an airtight condition between the semi-conductor image sense chip (30) and the glass plate (20). The top face (31) of the semi-conductor image sense chip (30) grows multiple bumps (311) thereon.

The glass plate (20) has a conductive interconnection circuit (21)

formed on the bottom face thereof. The conductive interconnection circuit (21) formed multiple first solder points (22) each aligning with a corresponding one of the multiple bumps (311). Each first solder points (22) is electrically connected to the corresponding one of the multiple bumps (311) by solder reflow technology. Further with reference to Fig. 4, the conductive interconnection circuit (21) has multiple second solder points (211) formed on one side of the bottom face of the glass plate (20).

The periphery and the bottom face are covered with an opaque mask (24). The opaque mask (24) has a through hole (not numbered) defined for allowing the semi-conductor image sense chip (30) extending through the through hole. The opaque mask (24) can prevent the light from entering the glass plate (20) and influencing the quality of the collected image from the semi-conductor image sense chip (30), and form an airtight condition around the semi-conductor image sense chip (30).

With reference to Fig. 5, the manufacturing process of the two above embodiments of the flip chip package structure for an image sensor is to divide a great glass plate (2) into multiple areas each forms a conductive interconnection circuit (21) thereon. With reference to Fig. 6, a semi-conductor image sense chip (10)/(30) is soldered on the multiple first solder points (22) by the way of flip chip and using SMT package equipment to make multiple solder points (22) being

electrically connected to the multiple bonding pads (111)/bumps (311).

The opaque mask (24) is not absolutely necessary to the present invention. To mount or not to mount an opaque mask (24) is in accordance with the downstream products of the flip chip package structure.

According to the flip chip package structure as shown in Figs. 1 and 2, the conductive interconnection circuit (21) can be disposed in a very narrowed width, and has a volume very close to that of the chip scale package (CSP) in a slight thickness because the conductive connection circuit (21) is formed by etching technology. Furthermore, the second solder points (211) can be greatly used to be soldered to a flexible printed circuit (FPC) and the second solder points (211) has an enlarged distance for enhancing the reliability of solder of the circuit board under a suitable design.

The second solder points (211) can be designed to different embodiments. With reference to Fig. 3, the second solder points (211) are arranged separately juxtaposed relative to one another. With reference to Fig. 4, the second solder points (211) are arranged in an array that can prevent the leads of the conductive interconnection circuit (21) from being soldered in a high density and reducing the reliability of soldering the FPC.

With reference to Fig. 7-9, the flip chip package structure (1)/(3) in accordance with the present invention can be used to an image sense

module. The image sense module comprises a lens set (4) secured on the flip chip package structure. The lens set (4) includes a holder (40) perpendicularly attached to a top face of the glass plate (20) and having a skirt (41) downward extending from the holder (40). A channel (411)
5 is defined in one side of the skirt (41) for allowing the conductive interconnection circuit (21) extending through the holder (40) and electrically connected to a FPC (50).

In the above image sense module, the plane top face of the glass plate can provide a good datum for the holder (40) for the light axis
10 perpendicularly projecting to the semi-conductor image sense chip (10), and the skirt (41) can accurately position the semi-conductor image sense chip (10) for controlling the image collect area located in a lens projecting area that has a low image fault.

Although the invention has been explained in relation to its
15 preferred embodiment, it is to be understood that many other possible modifications and variations can be made without departing from the spirit and scope of the invention as hereinafter claimed.